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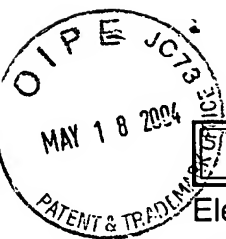
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Title of Invention: LEADFRAME FOR A SEMICONDUCTOR PACKAGE
First Named Inventor: HYUNG LEE
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Filing Date: 2004-02-09
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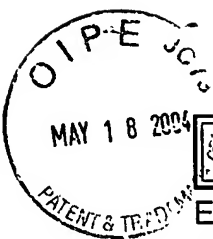
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TRANSMITTAL

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Title of Invention	LEADFRAME FOR A SEMICONDUCTOR PACKAGE									
Application Number: 10/774893 										
Date: 2004-02-09										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
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Documents being submitted	Files									
us-ids	ids5-usidst.xml									
	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of
Invention

LEADFRAME FOR A SEMICONDUCTOR PACKAGE

Application Number: 10/774893
Confirmation Number: 8761
First Named Applicant: HYUNG LEE
Attorney Docket Number: AMKOR006C
Art Unit: 2811

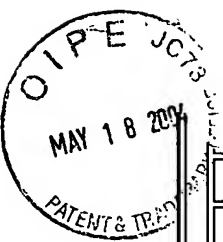


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or 6184573 or 6184465 or 6194777 or 6197615
or 6198171 or 6201186 or 6201292 or 6204554
or 6208023 or 6208020 or 6208021 or 6211462
or 6218731 or 6222258 or 6222259 or 6225146
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or 6309909 or 6316822 or 6316838 or 6323550
or 6326243 or 6326244 or 6326678 or 6335564
or 6337510 or 6339255).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date